

MICROSTAR

MICROSTAR EF8622

Fully Automatic High-Precision Eutectic Die Bonder

EF8622 is a fully automatic eutectic die bonder designed for high-precision, multi-chip packaging in optical communications and data center applications. It supports eutectic and dipping processes with $\pm 1.5\mu\text{m}@3\sigma$ accuracy, dual-station parallel operation, and 12-nozzle dynamic tool change. The system integrates an air-floating platform and dual-pulse heating to enhance alignment stability and thermal uniformity, with AGV and multi-carrier compatibility for high-yield, low-intervention production.



Key Features



High Precision

Equipped with an air-floating platform and vision system, combined with table-mapping compensation, achieving $\pm 1.5\mu\text{m}@3\sigma$ placement accuracy and $0.1\mu\text{m}$ repeatability.



High Efficiency

Dual-station operation with 12-nozzle dynamic tool change enables non-stop switching, reaching up to 144 UPH.



High Flexibility

Supports various die sizes and carriers; modular design and BOS interface allow flexible configurations.



High Adaptability

Compatible with magazine loading, AGV, and buffer switching; supports zero-time auto nozzle/dispenser change for multi-product production.

Applications



Optical Module



LiDAR Sensors



RF Devices



Power Devices



Laser Radar



Microwave Devices
& Antennas

Technical Specifications

EF8622		
Placement Accuracy		$\pm 1.5\mu\text{m}$ (Standard Die)
Bonding Process		Eutectic Bonding / Dipping Bonding
Equipment Efficiency		103-144 UPH(Eutectic)/240-300 UPH(Dipping)
Angular Accuracy		$\pm 0.15^\circ$
Application		COC/COS/Gold-Box
Chip Size		0.15x0.2mm-5x5mm
Substrate Size		16x16mm
Carrier Size		L:160-200mm/W:80-100mm
Machine Dimensions		2370mmx1210mmx1870mm(L x W x H)
Weight		2000Kg
Bonding System	Nozzles	12 nozzles, dynamic auto change
	Force Control	(10-100 g): ± 2 g;(100-500 g): $\pm 3\%$
Loading/Unloading System	Inline Integration	Magazine loading/unloading, AGV interface
	Barcode Function	Supports carrier barcode binding
Eutectic System	Working tables	2
	Transfer Stations	Up to 8 single bonding stages
	Heating Method	Pulse Heating
	Temperature Range	25-450°C
Feeding Modes	Heating Rate	80°C/s (adjustable heating/cooling rate)
	Wafer	6", standard: 2 units
	Waffle Pack/Gel-Pak	2", standard: 6 units



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